



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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PRODUCT NUMBER  
10076801-XXX-XXLF

PLATING

- 1 = 0.76µm GOLD/GXT ON CONTACT AREA, 2µm TIN MIN ON TAILS
- 4 = 2.0µm TIN MIN FULL PLATED
- 5 = 0.25µm GOLD/GXT ON CONTACT AREA, 2µm TIN MIN ON TAILS
- 8 = 0.38µm GOLD/GXT ON CONTACT AREA, 2µm TIN MIN ON TAILS

1.27µm NICKEL MIN UNDERLAYER FOR ALL PLATING VERSIONS

LEAD FREE & ROHS COMPATIBLE  
NOTE 7  
TOTAL NB OF POS 04 TO 72  
PACKAGING NOTE 3.

PIN STYLE	POST	SOLDER
01	5.84	2.50
02	6.75	2.50
03	5.84	3.00
04	6.75	3.00
05	7.70	3.00
06	8.20	3.00
07	10.50	3.20
08	9.10	3.00
09	5.84	2.00

NOTES:

1. HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0 COLOR: BLACK
2. PIN MATERIAL : PHOSPHOR BRONZE
3. PACKAGING OPTIONS:
  - POLY BAGS
  - A = TAPE & REEL WITH CAP, AS AVAILABLE
  - T = IN TUBE WITHOUT PICK-UP CAP
4. 9N MIN RETENTION IN EITHER DIRECTION
5. TO DETERMINE DIMENSIONS :  
N = NUMBER OF POSITIONS PER ROW  
EXAMPLE : 8 POS N x 2.54 = 20.32mm
6. UNDERPLATING : 1.27µm Ni MIN
7. ROHS COMPLIANT & COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

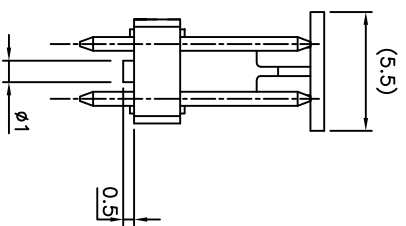
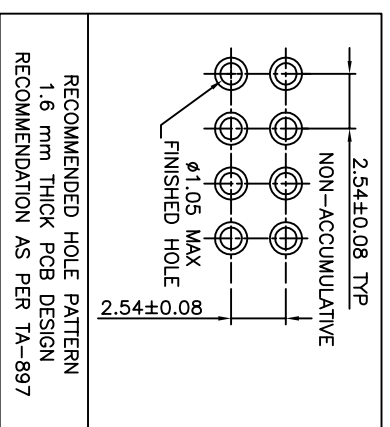
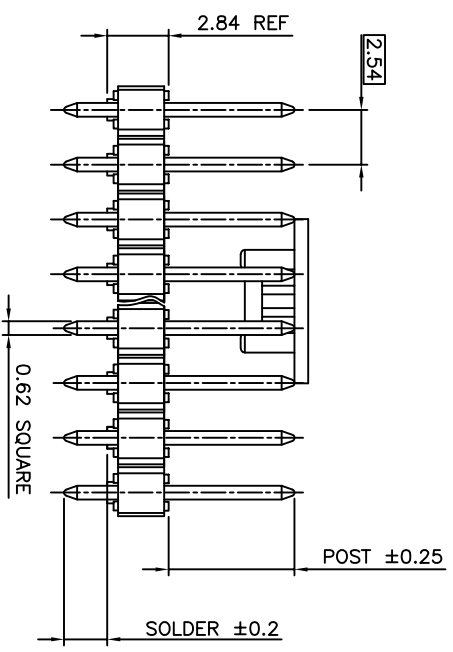
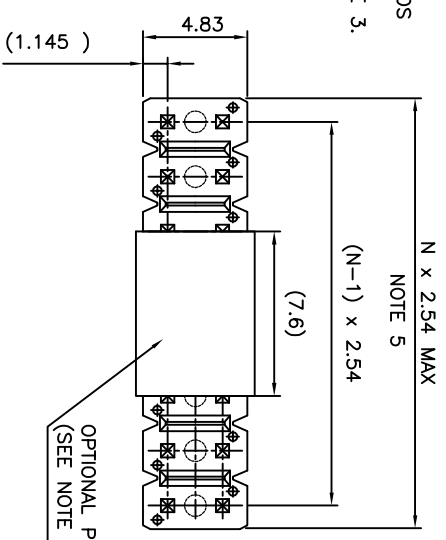
- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 30 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.

c - LABELING:

- MEETS PACKAGING SPECS AS PER GS-14-920
- d - LEGAL STATEMENT: SEE GS-47-0004



mat'l. code		surface		tolerance		projection		product family			
ltr	ecn no	dr	date	ISO 1302	ISO 406	ISO 1101	mm	title	type		
SEE NOTES											
A	F08-0104	LWU	08.01.15	tolerances unless otherwise specified	x ±0.3		mm	UNSHR. HEADER	customer		
B	F09-0072	JCO	09.07.23		xx ±0.15			DR STR PIN IN PASTE	customer		
C	B-17101	JCO	14.03.04		xxx ±0.05		scale 5:1				
D	B-18988	LWU	14.10.06								
E	F-23186	AMA	16.02.01								
sheet	revision	chf	P.NIZZI	chf	J.M.C	07.10.22					
sheet	revision	chf	J.M.C	chf	J.M.C	07.02.21					
index	sheet										
dwg no		sheet 1 of 1		size							
10076801		A3									